

GLASS PASSIVATED SURFACE MOUNT BRIDGE RECTIFIERS

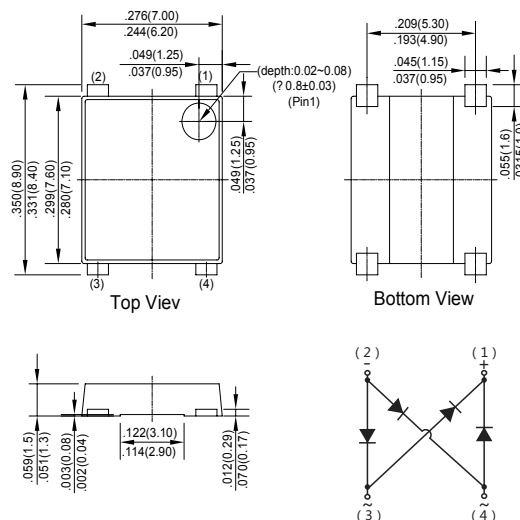
Features

- ◆ Glass Passivated Chip Junction
- ◆ Reverse Voltage - 60 V
- ◆ Forward Current - 5.0 A
- ◆ High Surge Current Capability
- ◆ Designed for Surface Mount Application

UMSB
RoHS
COMPLIANT

Mechanical Data

Case : JEDEC UMSB molded plastic body
 Terminals : Solderable per MIL-STD-750, Method 2026
 Polarity : Polarity symbol marking on body
 Mounting Position : Any
 Weight : 0.00824 ounce, 0.2337 grams



Maximum Ratings And Electrical Characteristics

Ratings at 25°C ambient temperature unless otherwise specified.

Single phase half-wave 60Hz, resistive or inductive load, for capacitive load current derate by 20%.

Parameter	Symbols	MDD MSB56	Units
Marking Code			
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	60	V
Maximum RMS voltage	V_{RMS}	42	V
Maximum DC Blocking Voltage	V_{DC}	60	V
Maximum Average Forward Rectified Current	I_O	5	A
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load (JEDEC Method)	I_{FSM}	80	A
Maximum Forward Voltage @ $I_F = 3A$ @ $I_F = 5A$	V_F	0.45(TYP) 0.59	V
Maximum DC Reverse Current at Rated DC Blocking Voltage @ $T_a = 25^\circ C$	I_R	0.3	mA
Typical Junction Capacitance (Note 1)	C_j	300	pF
Operating Temperature Range	T_j	-55 ~ +150	°C
Storage Temperature Range	T_{stg}	-55 ~ +150	°C

Note: 1. Measured at 1MHz and applied reverse voltage of 4 V D.C.

2. Mounted on glass epoxy PC board with 4×1.5"×1.5" (3.81×3.81 cm) copper pad.

Typical Characteristics

Fig.1 Average Rectified Output Current Derating Curve

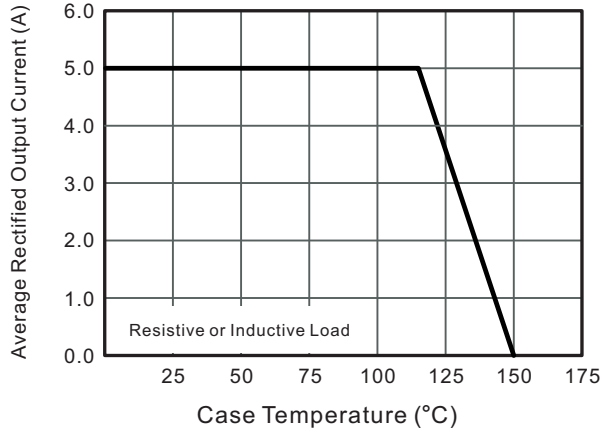


Fig.2 Typical Reverse Characteristics

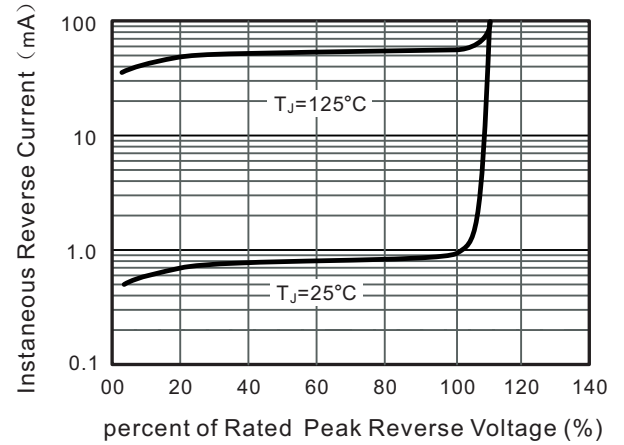


Fig.3 Typical Instaneous Forward Characteristics

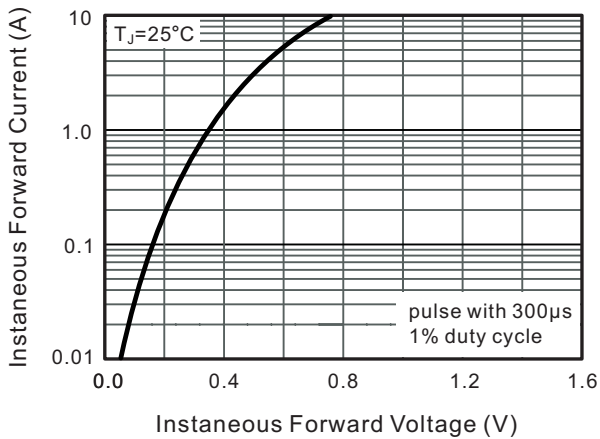


Fig.4 Typical Junction Capacitance

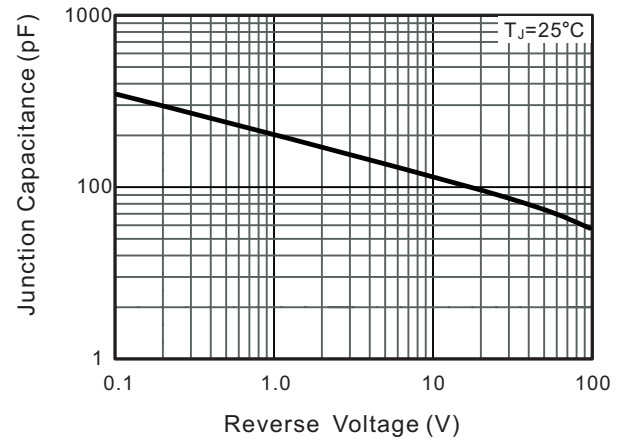
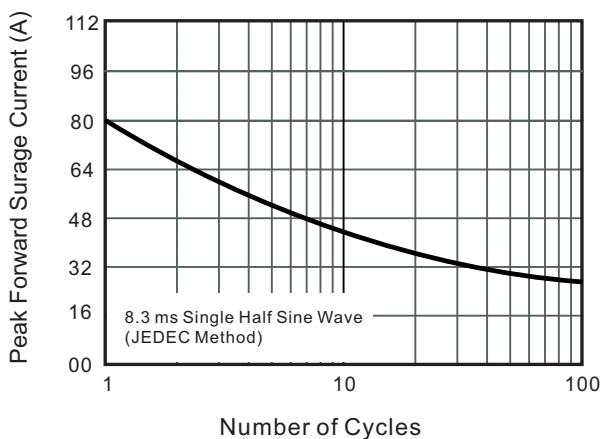
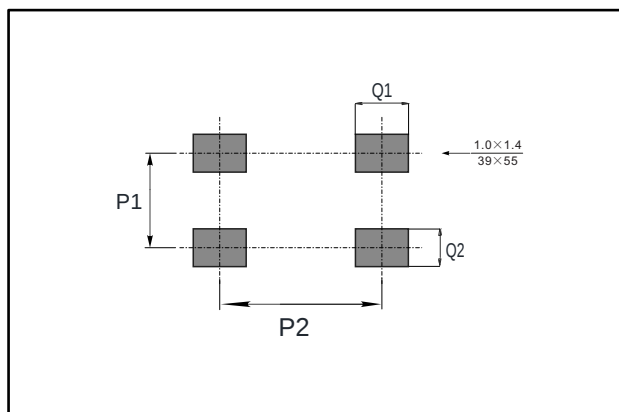


Fig.5 Maximum Non-Repetitive Peak Forward Surge Current



The curve above is for reference only.

Suggested Pad Layout



Dim	Min
P1	5.1
P2	7.1
Q1	1.8
Q2	1.3